

## PATENT ABSTRACTS OF JAPAN

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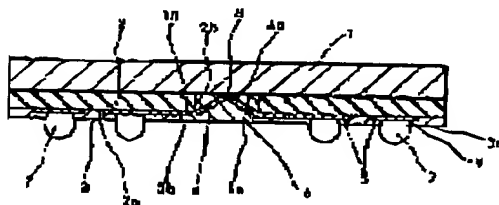
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## (54) SEMICONDUCTOR DEVICE

## (57)Abstract:

PROBLEM TO BE SOLVED: To reduce rigidity of an electric connection part member, and relax thermal strain due to deformation, by shifting the end surface of a bonding part member facing an electrode on a semiconductor element, more adjacently to the electrode than the end surface of the sheet type part member on the same side adjacent to the end surface of bonding part member.

SOLUTION: An end surface 2b on an electrode 8 side of a bonding part member 2 protrudes more adjacently to the electrode 8 than an end surface 3b on the electrode 8 side of a sheet type part member 3 which is adjacent to the end surface 2b, and the positions of both end surfaces are shifted to each other. A lead 4 stretches in the horizontal direction (direction parallel to a circuit forming surface 1a of the semiconductor element), along a contact surface 2a with the sheet type part member 3 of the bonding part member 2, from an end surface 3b of the sheet type part member 3, forms a lead horizontal part 10, bends at the edge part of the end surface 2b of the bonding part member 2, and is bonded to the electrode 8. The lead can be lengthened and rigidity of the lead is reduced, so that distortion generated in the lead which is caused by the deformation of the bonding part member can be relieved by the deformation of the lead itself.



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